PCN Number:	20171204000	PCN Date:		December 13, 2017			
Title: Datasheet for TPS25940-Q1							
Customer Contact:	PCN Manager				ept:	Quality Services	
Change Type:							
Assembly Site		Design				r Bump Site	
		Data She			Wafer Bump Material		
Assembly Materials			ber change			r Bump Process	
Mechanical Specification		Test Site			Wafer Fab Site		
Packing/Shipping/Labeling		Test Proc	ess			r Fab Materials	
Notification Details						r Fab Process	
Description of Change:							
Texas Instruments Incorporated is announcing an information only notification.							
The product datasheet(s) is being updated as summarized below. The following change history provides further details.							
TEXAS INSTRUMENTS TPS25940-Q1 SLVSDJ08-MAY 2010-REVISED NOVEMBER 2017							
Changes from Revision A (June 2016) to Revision B Page • Added subsection 9.2.4.3 Overload Detection Using TPS25940-Q1 to the Application Information section 1							
The datasheet number will be changing.							
Device Family		Change From:			Change To:		
TPS25940-Q1	,		SLVSDJ0A			SLVSDJ0B	
These changes may be reviewed at the datasheet links provided.							
http://www.ti.com/product/TPS25940-Q1							
Reason for Change:							
To accurately reflect device characteristics.							
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):							
No anticipated impact. This announcement notifying another application use case for this device.							
There are no changes to the actual device. Changes to product identification resulting from this PCN:							
None.							
Product Affected:							
TPS25940AQRVCRQ1	TPS25940AQR	VCTQ1					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com